

Product specification

Product:	Conductive silver paste
Part number:	01L-2608B

Application scope :

Single-component conductive paste series, a conductive silver paste with reliable adhesion for chip fixation. This paste is suitable for bonding various chips onto substrates such as circuit boards, glass, and ceramics, exhibiting excellent compatibility with the substrate without sagging. Electrodes fabricated with this paste exhibit a glossy, fine appearance and dense structure after curing.

Usage conditions:

Substrate	Circuit, Glass, Ceramic, Metal
Usage method	Dispensing, printing
Leveling	Level at room temperature for 5-10 minutes (time adjusted according to actual leveling conditions)
Solidify	Furnace drying at 150–200°C for 30 minutes (the curing temperature can be within the range of 150–200°C, and the curing time may be adjusted according to actual conditions)
Thinner	ST-1001

Characteristics:

1. Paste Characteristics:

Characteristic		Standard	Test method and conditions
1	Fineness	$\leq 15\mu\text{m}$	FOG test
2	Viscosity	80-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operating at 10rpm and $25\pm 1^\circ\text{C}$, with adjustable viscosity according to user requirements.
3	Solid content	70	Silver

2. Characteristics after curing:

Under the condition of 1 sintering , Check fired film produced under the conditions specified in 1) ,

Characteristics		Standard	Test method and conditions
4	Resistivity	$\leq 30\text{m}\Omega/\square$	
5	Hardness	4H	Pencil hardness
6	Shear strength	12Mpa	

Save conditions and validity period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of six months from the date of shipment.

Packaging method:

Standard packaging: 1000g per can. Sample available in 200g small can packaging.